CLAIMS

What is claimed is:

1. An interconnect hub comprising:

a first side;

a second side opposite the first side to couple with the three or more dies, and wherein the second side includes a plurality of electrical couplings to electrically couple at least one of the three or more dies to another of the three or more dies; and

wherein the electrical couplings are to facilitate data transfer between at least a subset of the three or more dies;

wherein a corner of the second side of the interconnect hub is to physically couple with a corner of the three or more dies;

wherein the three or more dies are tiled dies; and

wherein the interconnect hub is positioned between the tiled dies and the substrate.

2. The interconnect hub of claim 1, wherein a subset of the plurality of electrical couplings are coupled with routing channels to facilitate direct communication between a first of the three or more dies and a second of the three or more dies.

3. The interconnect hub of claim 1 or claim 2, wherein the interconnect hub is a silicon bridge or interposer.

4. The interconnect hub of any one of claims 1 to 3, wherein the three or more dies are a same die rotated 90, 180, or 270 degrees.

5. The interconnect hub of any one of claims 1 to 4, wherein the interconnect hub includes at least one active component or at least one passive component.

6. The interconnect hub of any one of claims 1 to 5, wherein data transfer includes high-speed IO data transfer.

7. A system comprising:

a substrate;

three or more dies; and

an interconnect hub physically coupled to the three or more dies, the interconnect hub comprising:

a first side;

a second side opposite the first side to couple with the three or more dies, and wherein the second side includes a plurality of electrical couplings to electrically couple at least one of the three or more dies to another of the three or more dies;

wherein the electrical couplings are to facilitate data transfer between at least a subset of the three or more dies;

wherein a corner of the second side of the interconnect hub is to physically couple with a corner of the three or more die;

wherein the three or more dies are tiled dies; and

wherein the interconnect hub is positioned between the titled dies and the substrate.

8. The system of claim 10, wherein a subset of the plurality of electrical couplings are coupled with routing channels to facilitate direct communication between a first of the three or more dies and a second of the three or more dies.

9. The system of claim 10 or claim 11, wherein the interconnect hub is a silicon bridge or interposer.

10. The system of any one of claims 10 to 12, wherein the three or more dies are a same die rotated 90, 180, or 270 degrees.

11. The system of any one of claims 10 to 13, wherein the interconnect hub includes at least one active component or at least one passive component.

12. The system of any one of claims 10 to 14, wherein data transfer includes high-speed IO data transfer.

13. A method comprising:

positioning three or more dies in a tiled formation within a plane; and

electrically coupling a side of an interconnect hub to a side of the three or more dies, wherein the plane of the interconnect hub is substantially parallel to the plane of the dies in the tiled formation to facilitate high-speed data transfer between the dies;

wherein electrically coupling further includes physical coupling to a corner of each of the three or more dies; and

wherein the interconnect hub is between the dies in the tiled formation and a substrate.

14. The method of claim 13, wherein electrically coupling the side of the interconnect hub to a side of the three or more dies further includes electrically coupling the side of the interconnect hub to an active side of the three or more dies.